



NREL PV Module Reliability Workshop,

Golden, Feb 26/27, 2013

PID Failure of c-Si and Thin-Film Modules and Possible Correlation with Leakage Currents

Peter Lechner

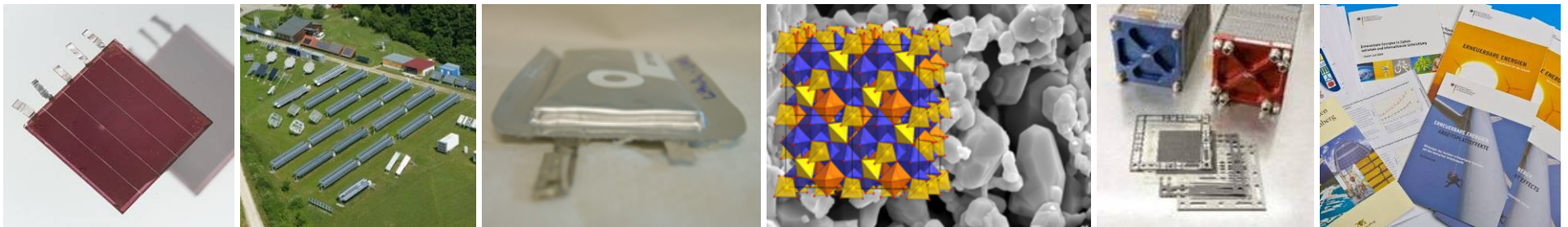
Zentrum für Sonnenenergie- und Wasserstoff-Forschung
Baden-Württemberg (ZSW)
Stuttgart, Germany

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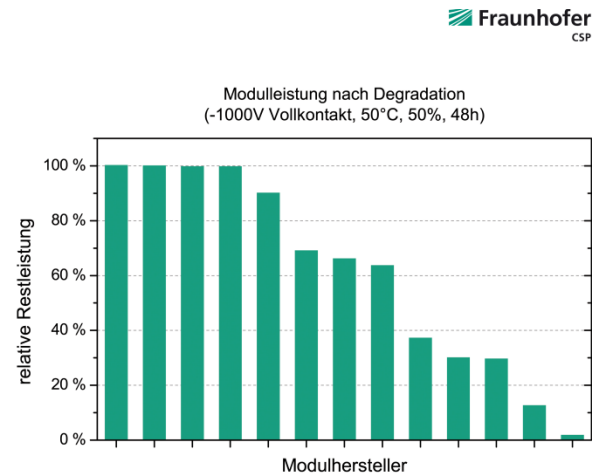
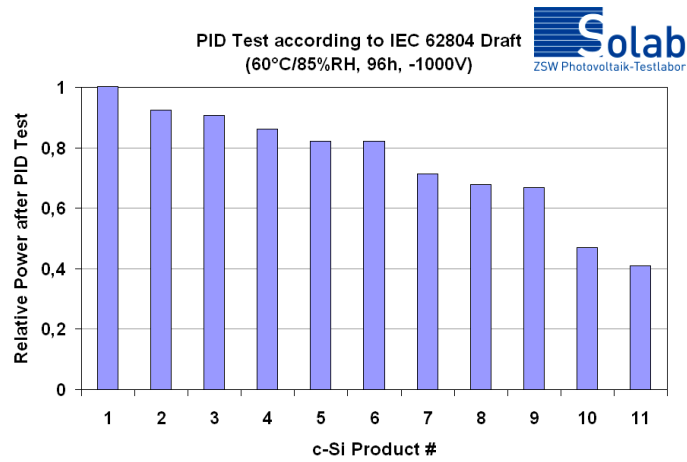
ZSW is a non-profit foundation with 200 employees

- The focus is on
- Photovoltaics – Thin-Film Technology
 - Fuel Cells and Hydrogen Technology
 - Electrochemical Storage
 - Renewable Fuels and Reformers
 - System Analysis and Consulting

We work on the whole value chain:
From materials science to production and product development.



FAQs:



Source: Fraunhofer CSP, 2012

- Relation between different PID lab-tests and PID in the field?
- Is transferred charge a degradation indicator
=> time-to-failure estimation?
- Role of reversible effects?
- Thin-film tests to be based on the IEC Draft 62804 for c-Si?

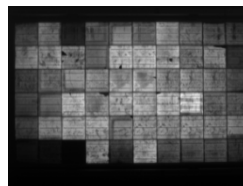
Outline

- PID failure of c-Si and thin film
- Power degradation
- Evaluation of leakage currents from lab and field
- Does PID match with charge?
- Recovery effects



PID failure of c-Si and thin film modules

	c-Si	Si-TF (a-Si, μ morph) CdTe	CIGS
Degradation effect	Power loss	Power loss; Delamination	Power loss
Defect location	SixNy	TCO	CIGS
Trigger	Leak. Current	Leak. current; Moisture	Leak. current



Approach

Indoor (climate chamber)

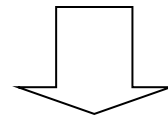
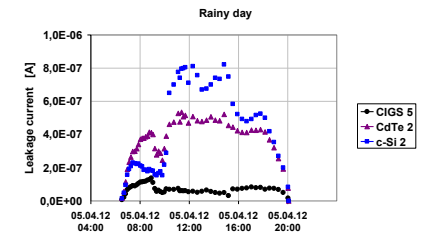
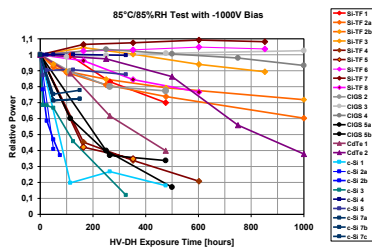
Leakage current (T-, RH-matrix)
Power loss (STC and low light)
Recovery

Bias -1000 V

Field (Widderstall)

Leakage current (5min sampling)
Power loss (flasher)

Bias up to -800V (PV- Generator)



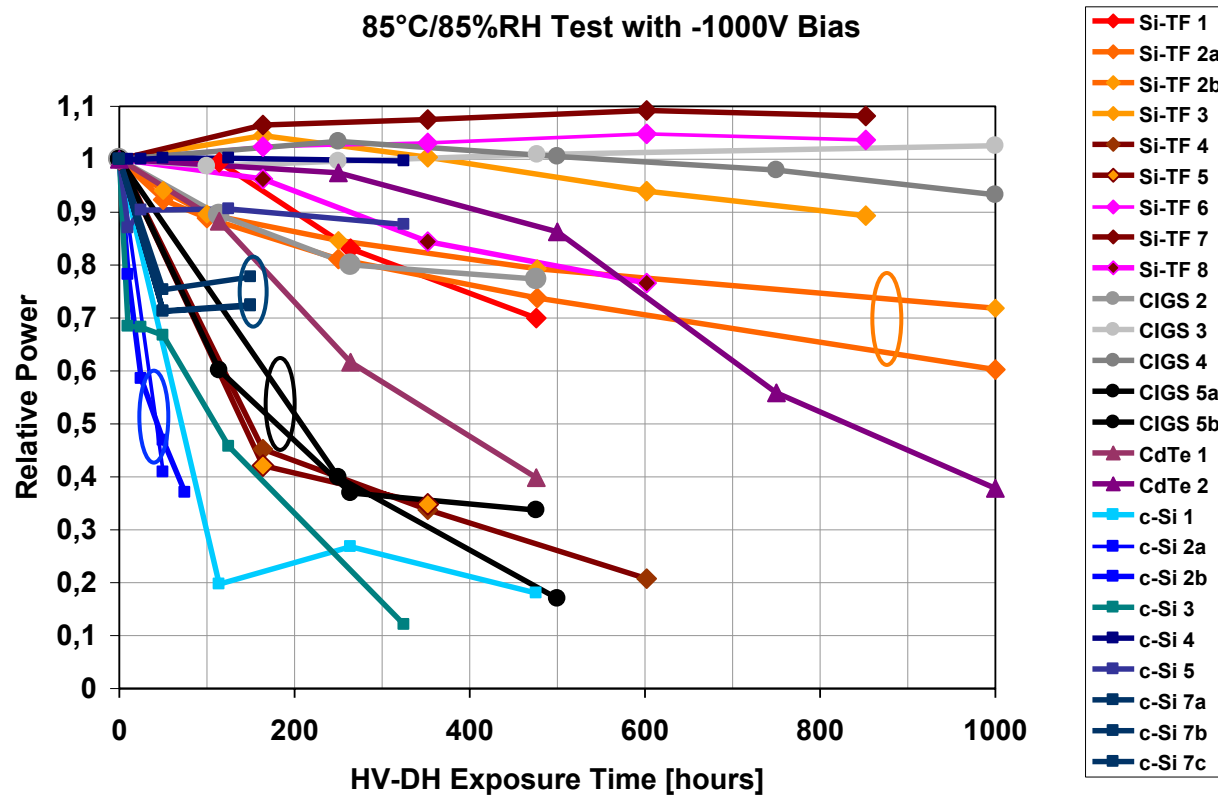
Time-to-PID-failure?

Outline

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- **Power degradation**
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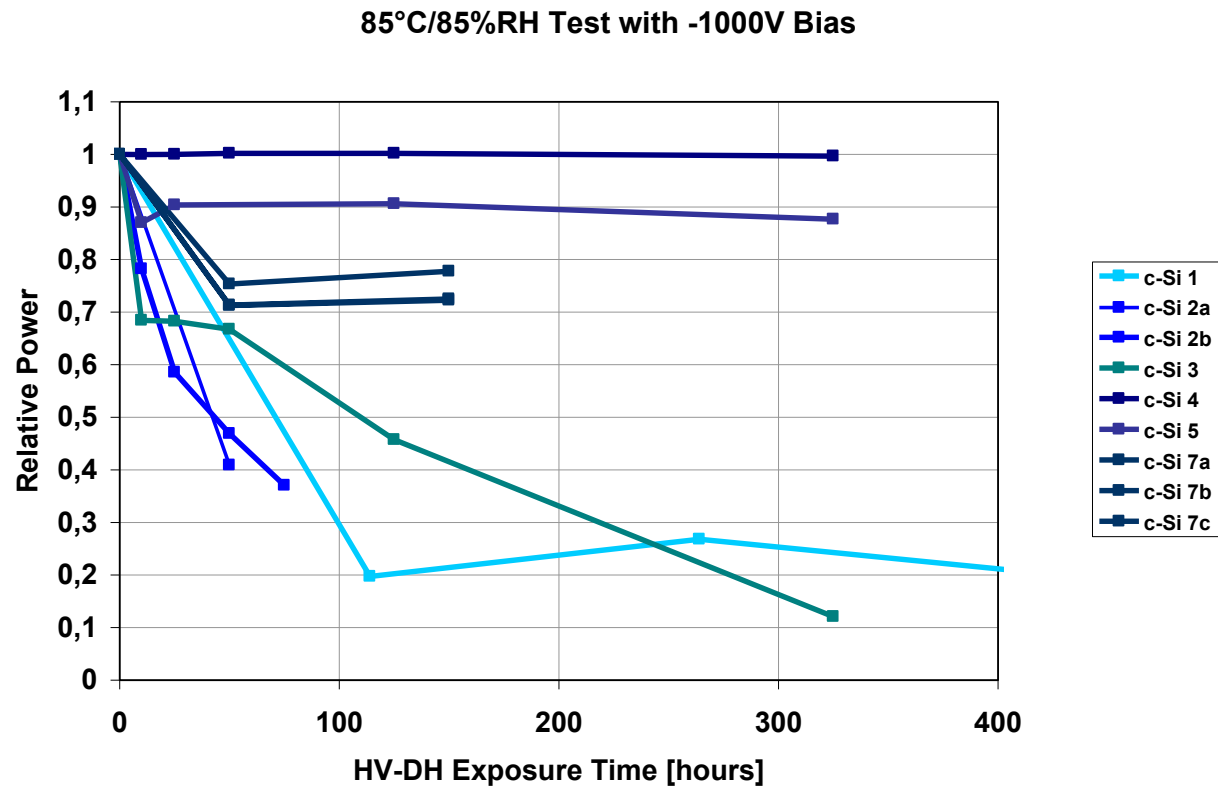


Module power after 85°C/85%-PID test: all technologies



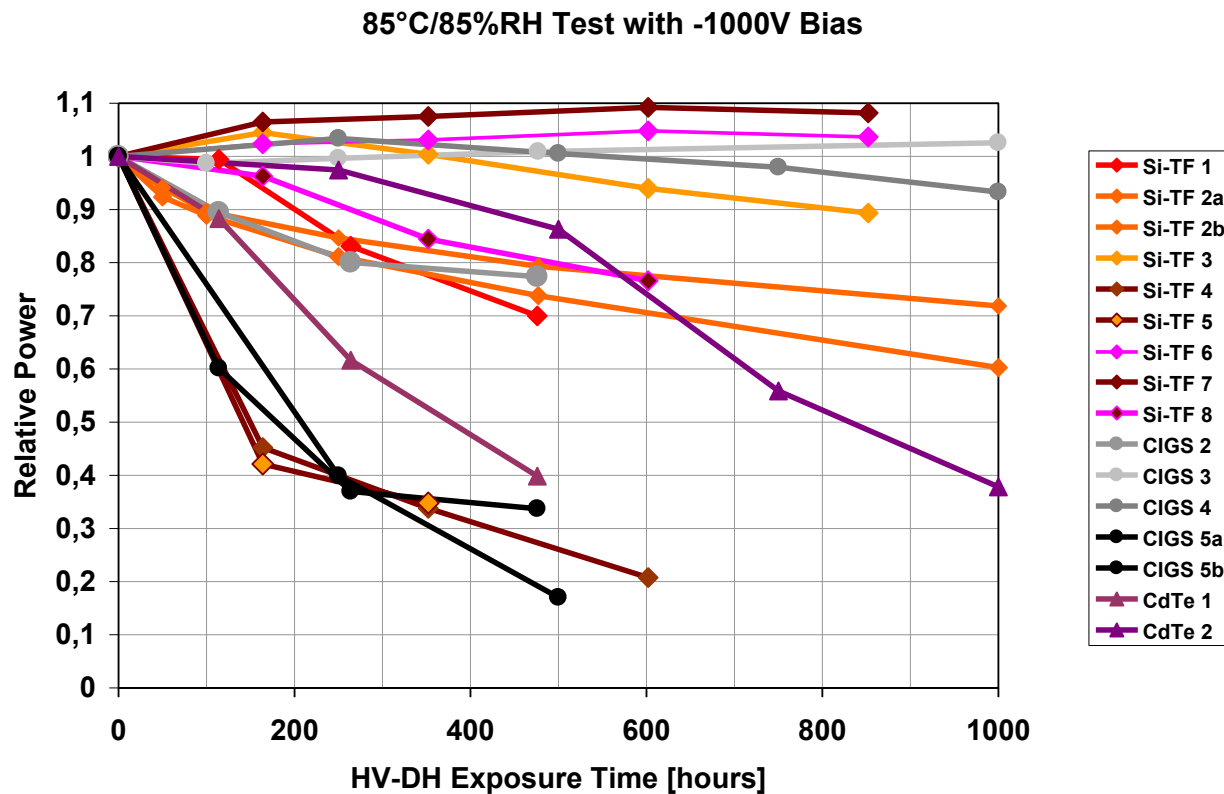
- Wide variation from stable to highly PID susceptible
- Reproducibility of PID failure is quite o.k.

Module power after 85°C/85%- PID test: c-Si only



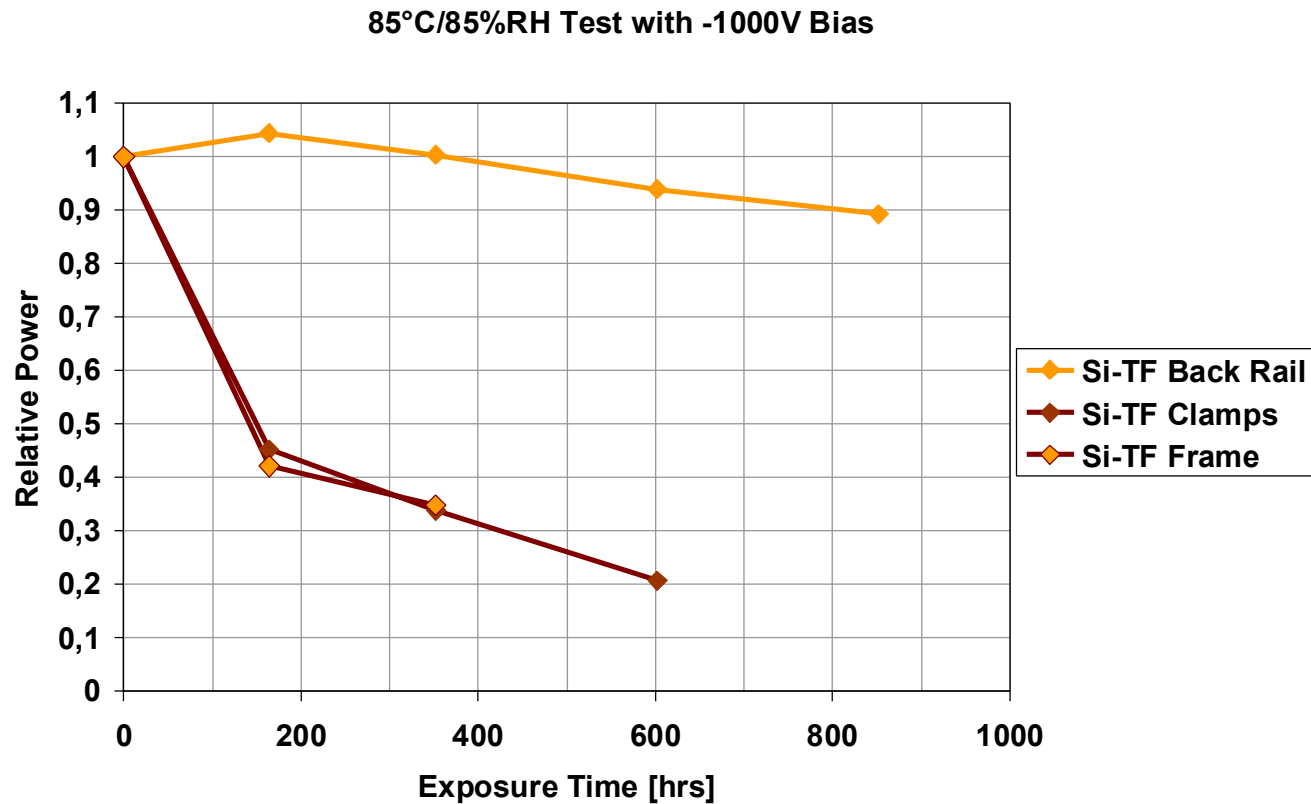
- Shunting occurs (loss of FF, Rsh, very bad at weak light)

Module power after 85°C/85%- PID test: TF only



- TCO corrosion occurs for some Si-TF and CdTe products
- Shunting occurs for some CIGS products; no visual defects
- For most of the PID-susceptible TF modules grounding is mandatory

Optimization of PID-resistivity by choice of mounting: Si-TF module



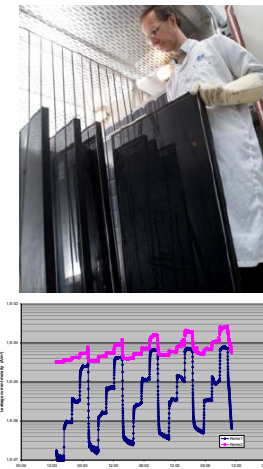
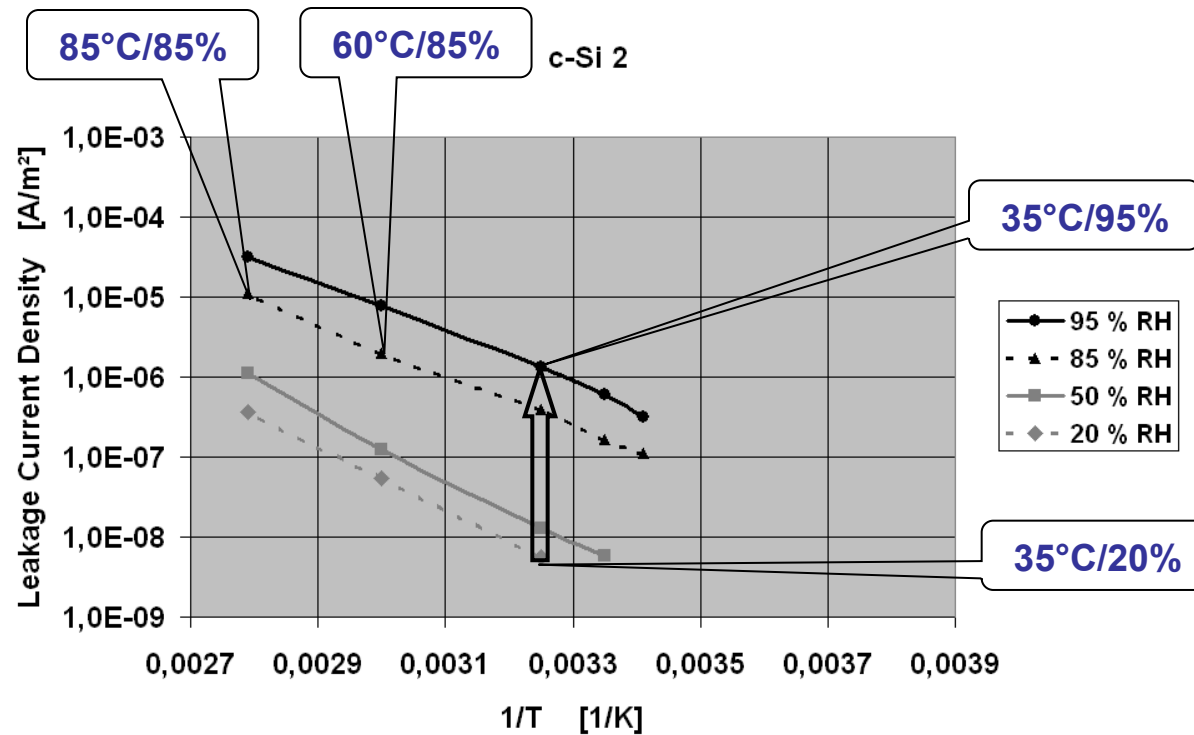
- Back Rail mounting reduces susceptibility for TCO-corrosion

Outline

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Arrhenius plot of leakage currents from the lab:

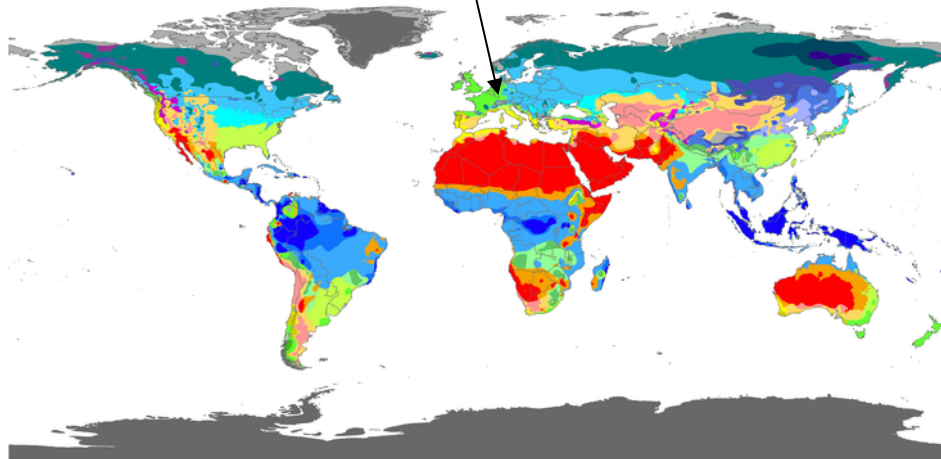


- Activation energy E_a typically between 0.6 and 0.8 eV
- Current is strongly dependent on humidity

Evaluation of leakage currents in the field

Location: Widderstall, Southern Germany
 9.713°E, 48.537°N, 750m AMSL

World map of Köppen-Geiger climate classification

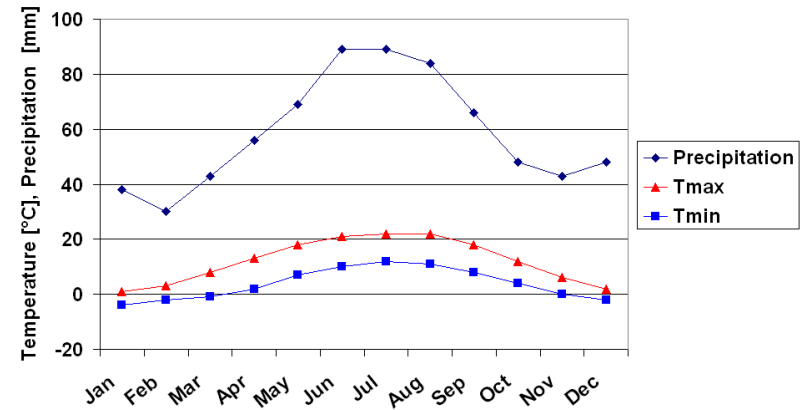


Af	BWh	Csa	Cwa	Cfa	Dsa	Dwa	Dfa	ET
Am	BWk	Csb	Cwb	Cfb	Dsb	Dwb	Dfb	EF
Aw	BSh	Cwc	Cfc	Dsc	Dwc	Dfc		
BSk				Dsd	Dwd	Dfd		

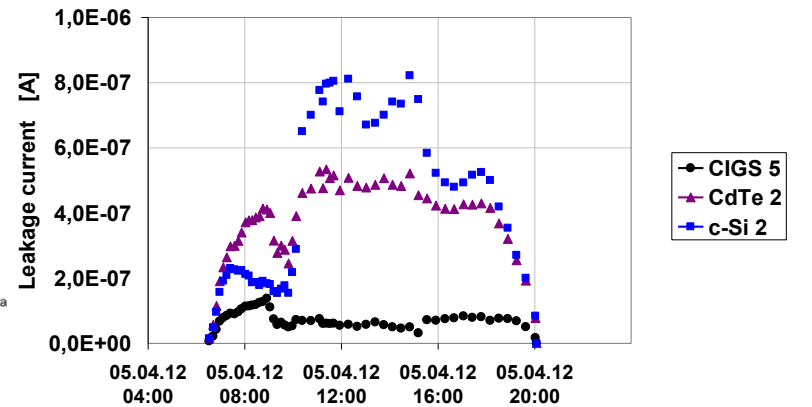
Contact : Murray C. Peel (mpeel@unimelb.edu.au) for further information

DATA SOURCE : GHCN v2.0 station data
 Temperature (N = 4,844) and
 Precipitation (N = 12,396)
 PERIOD OF RECORD : All available
 MIN LENGTH : ≥30 for each month.
 RESOLUTION : 0.1 degree lat/long

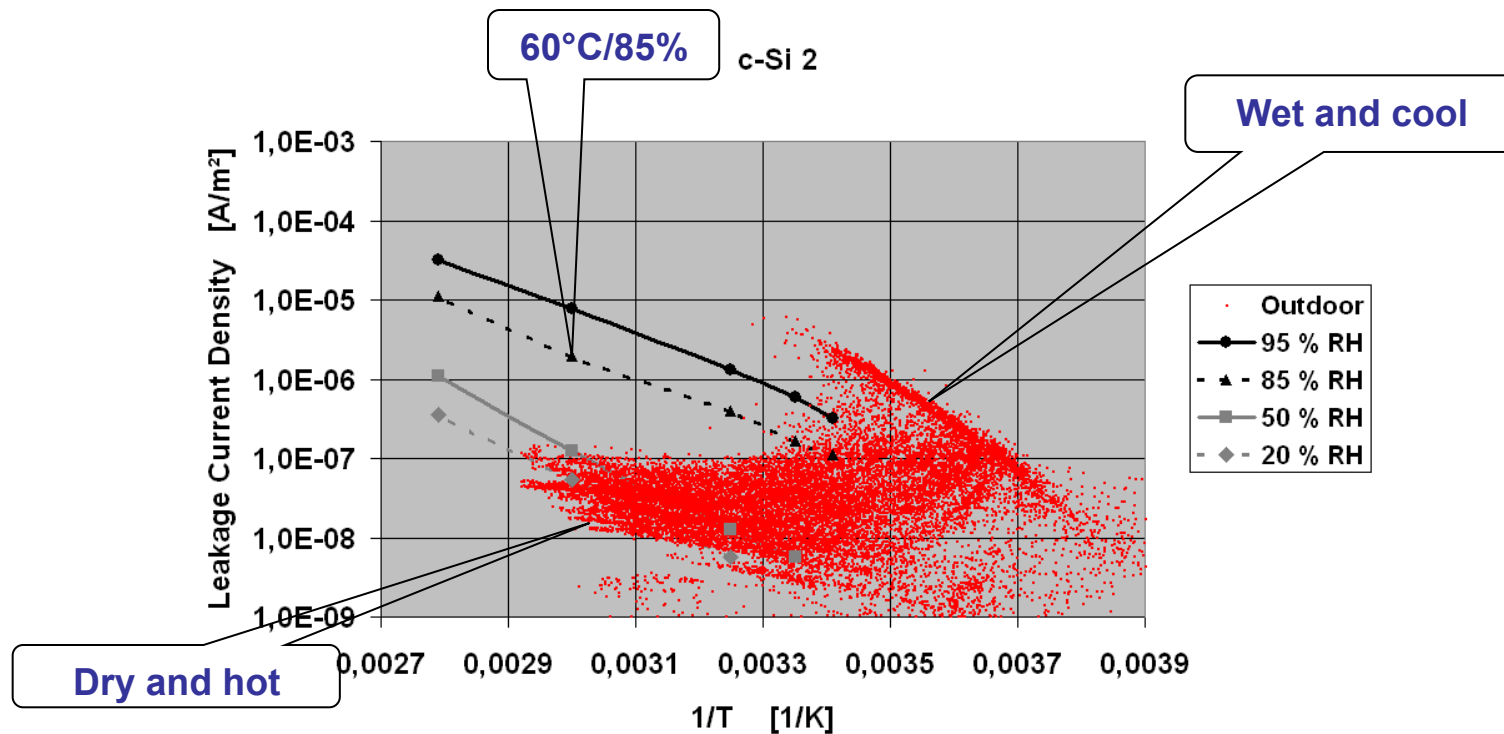
Location: Widderstall, Germany



Rainy day

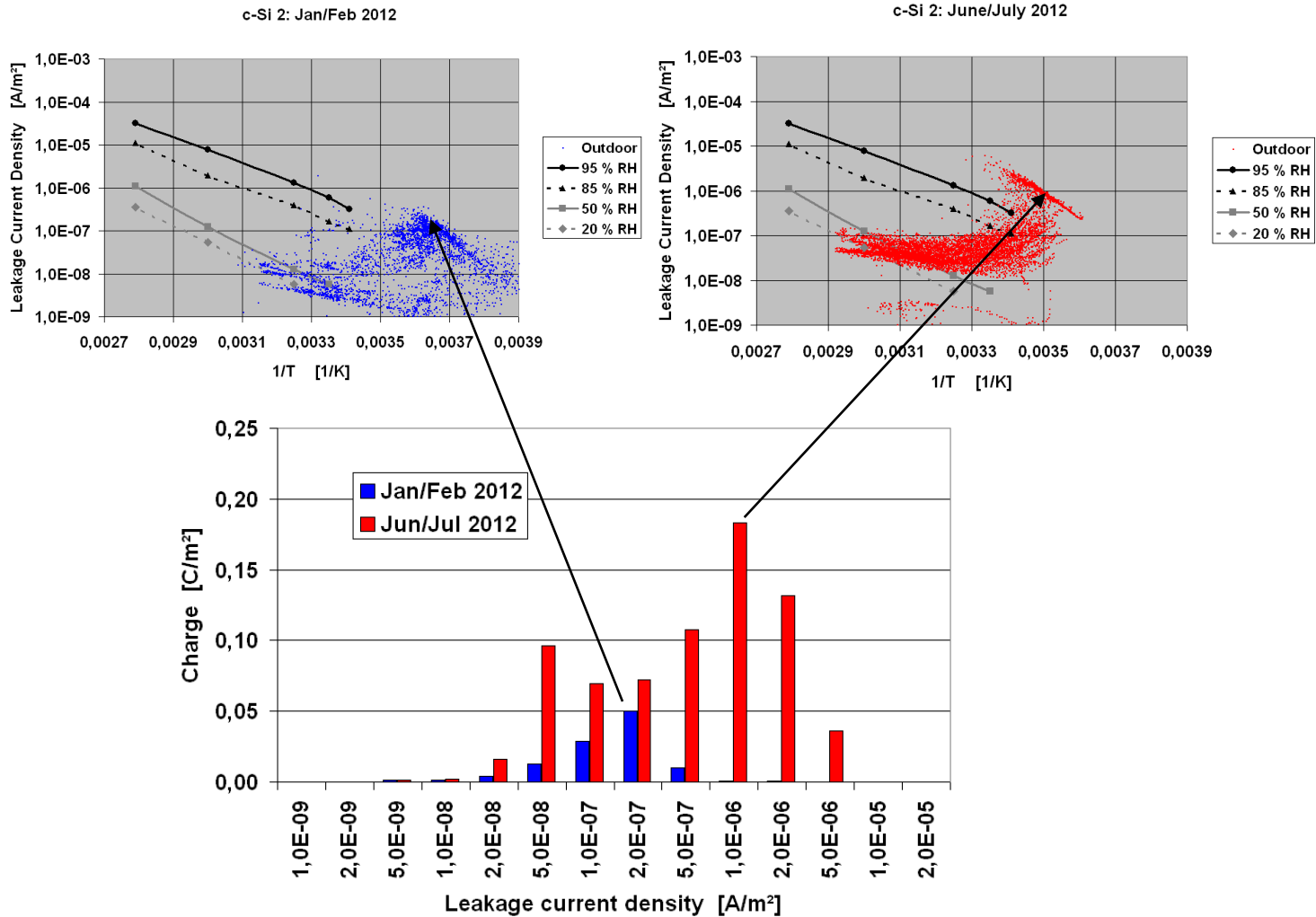


Superposition of chamber and field measurements Outdoor from Jan to Jul 2012



- High currents for wet and cool modules
- Low currents for dry and hot modules
- Moderate “acceleration” at 60°C/85% vs. “wet and cool”

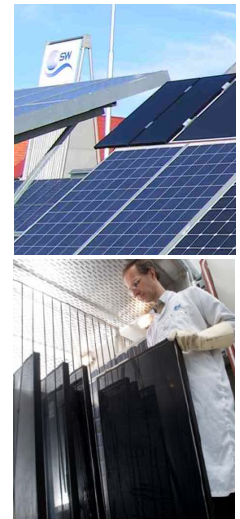
Summer/winter distribution of leakage currents and charge



- major contribution to transferred charge stems from wet/cool modules

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- **Does PID match with charge?**
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Estimation of time to 90% initial power (P90)

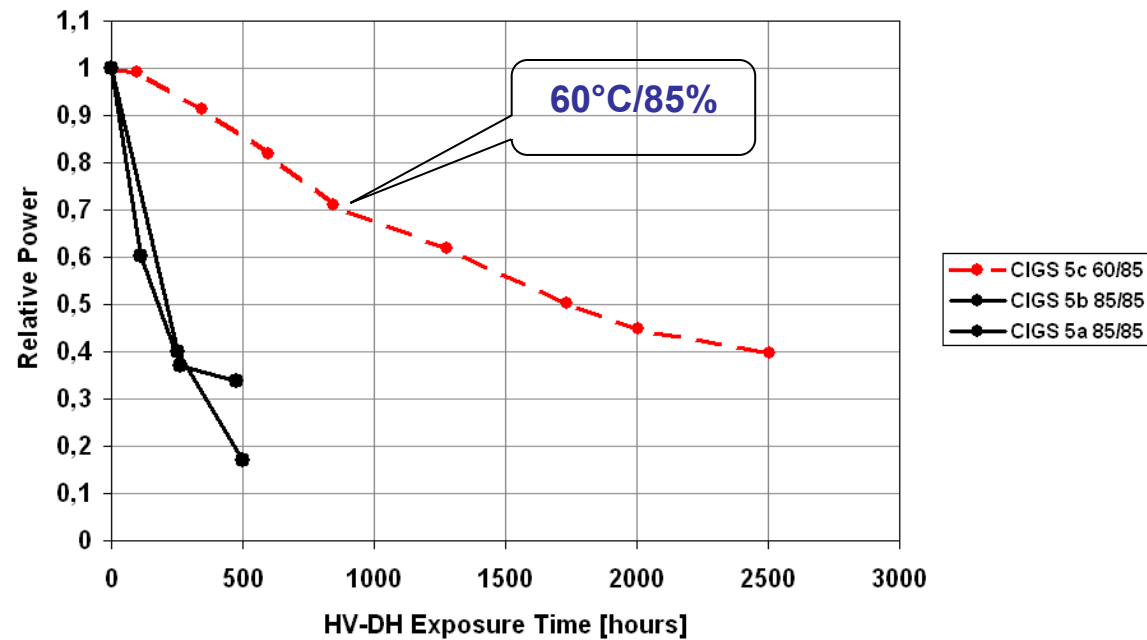
- If charge transfer would be the only PID-trigger -

Module type	Q from 85/85 for P90 [C/m ²]	Qd from Outdoor [mC/m ²]	Outdoor time)* to Q for P90 [yrs]
c-Si 2	0.6	7.5	0.2
Si-TF 2	33	32	2.8
CIGS 5	1.4	1.3	3.1
CdTe 2	23	6.1	10
CIGS 4	> 87	0.6	> 4*E2
CIGS 3	> 37	0.25	> 4*E2
Si-TF 6	> 300	1.4	> 5*E2

)* valid for location Widdersstall, at about -800V Potential

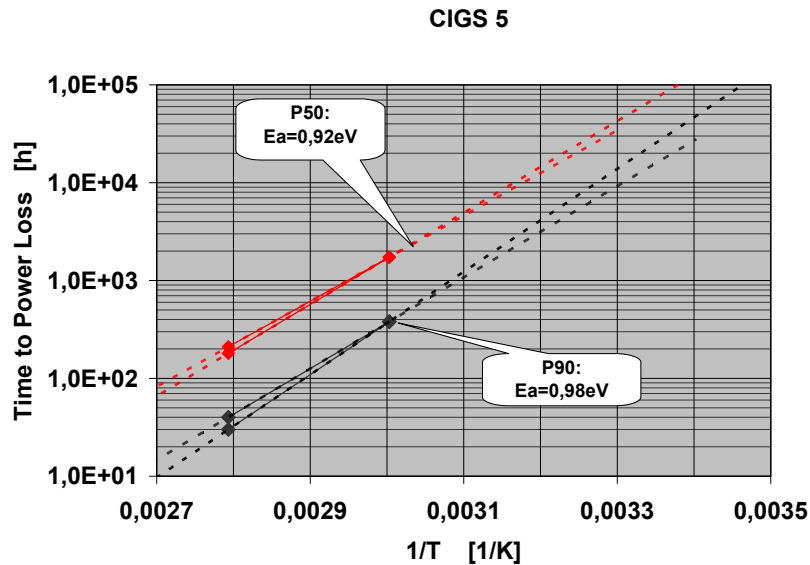
Does PID match with transferred charge? Example: CIGS 5

CIGS 5: 60/85/-1000 and 85/85/-1000

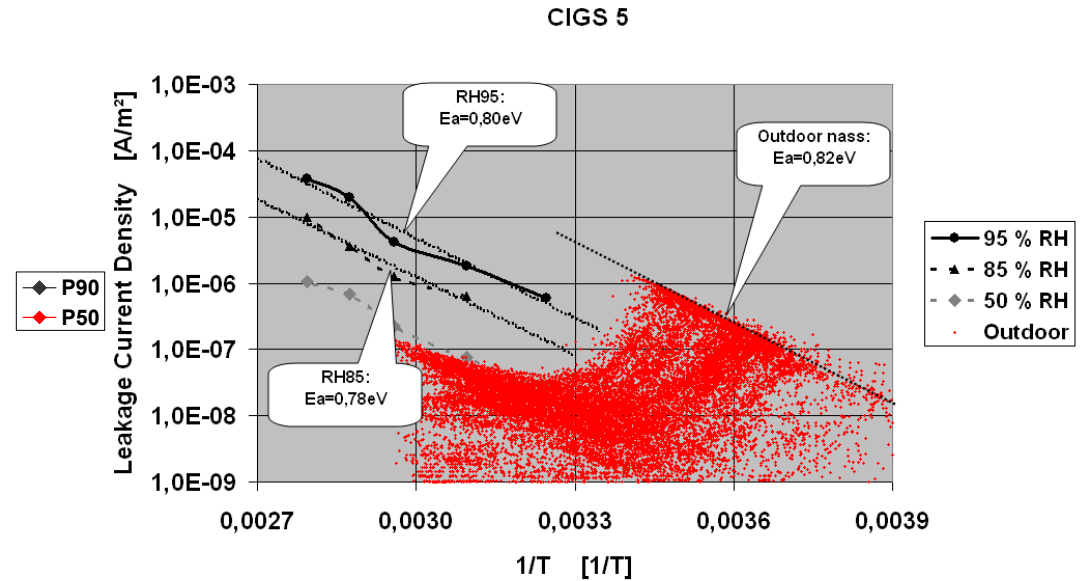


Power loss vs. time

Activation energy for power loss and leakage currents CIGS 5



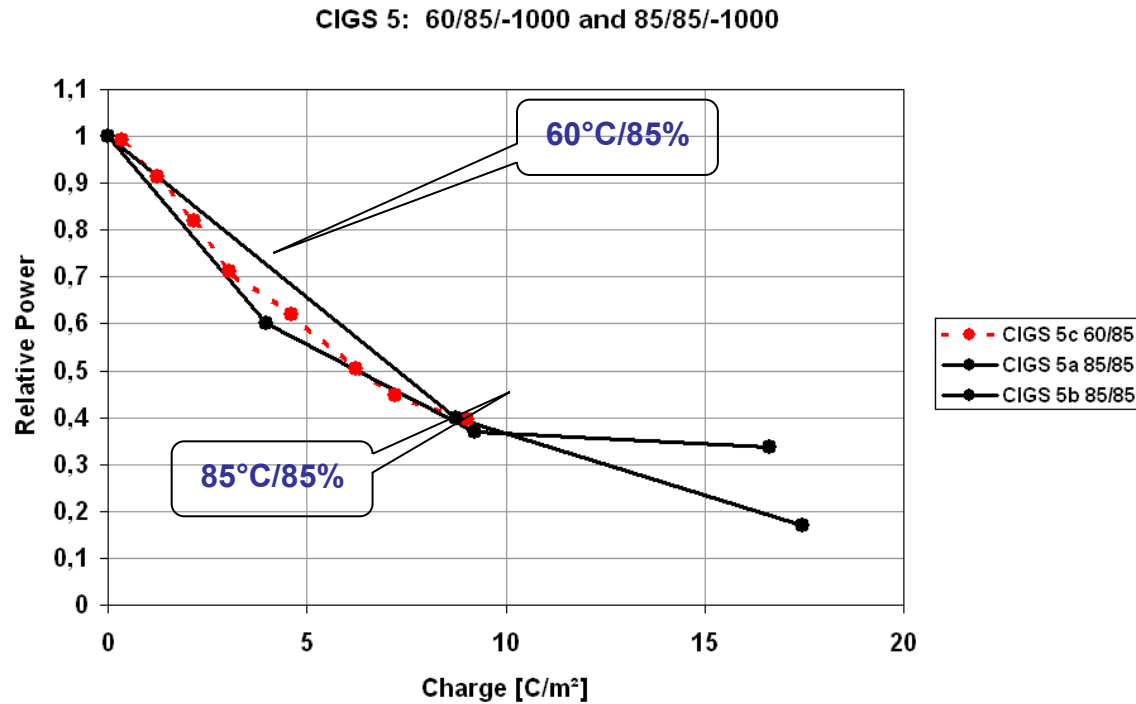
P-loss:
 $E_a = 0.92 \dots 0.98\text{eV}$



Leakage current:
 $E_a = 0.78 \dots 0.82\text{eV}$

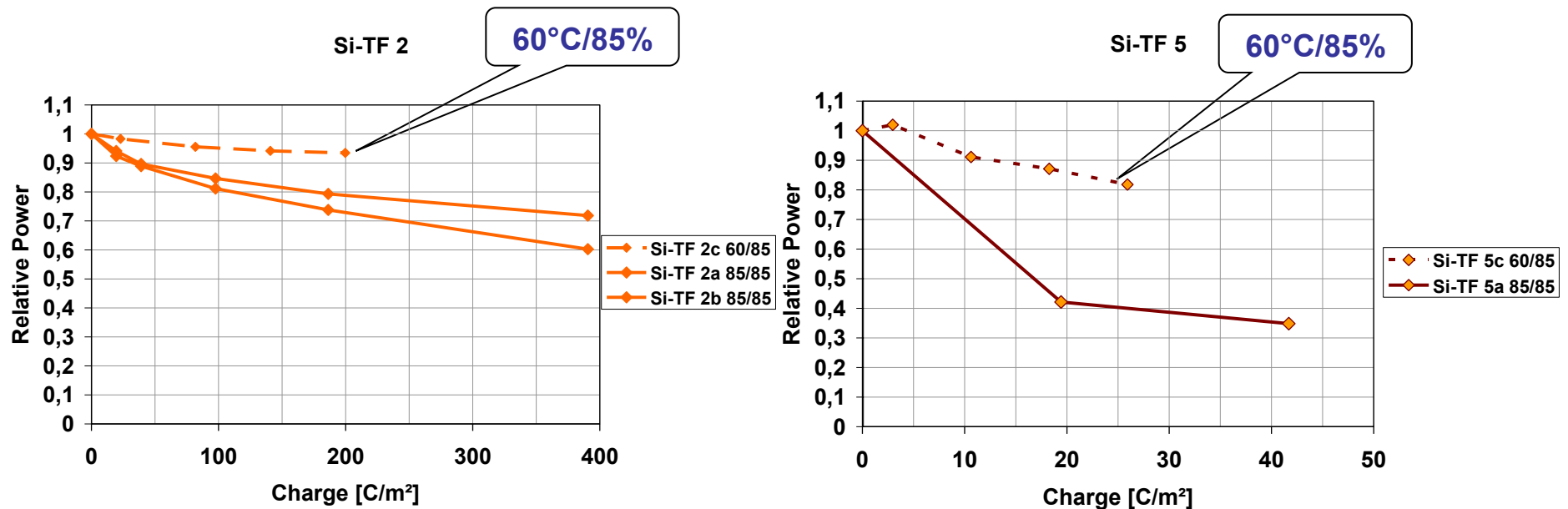
- E_a similar for P-losses and temperature activated leakage current

PID vs. charge CIGS 5



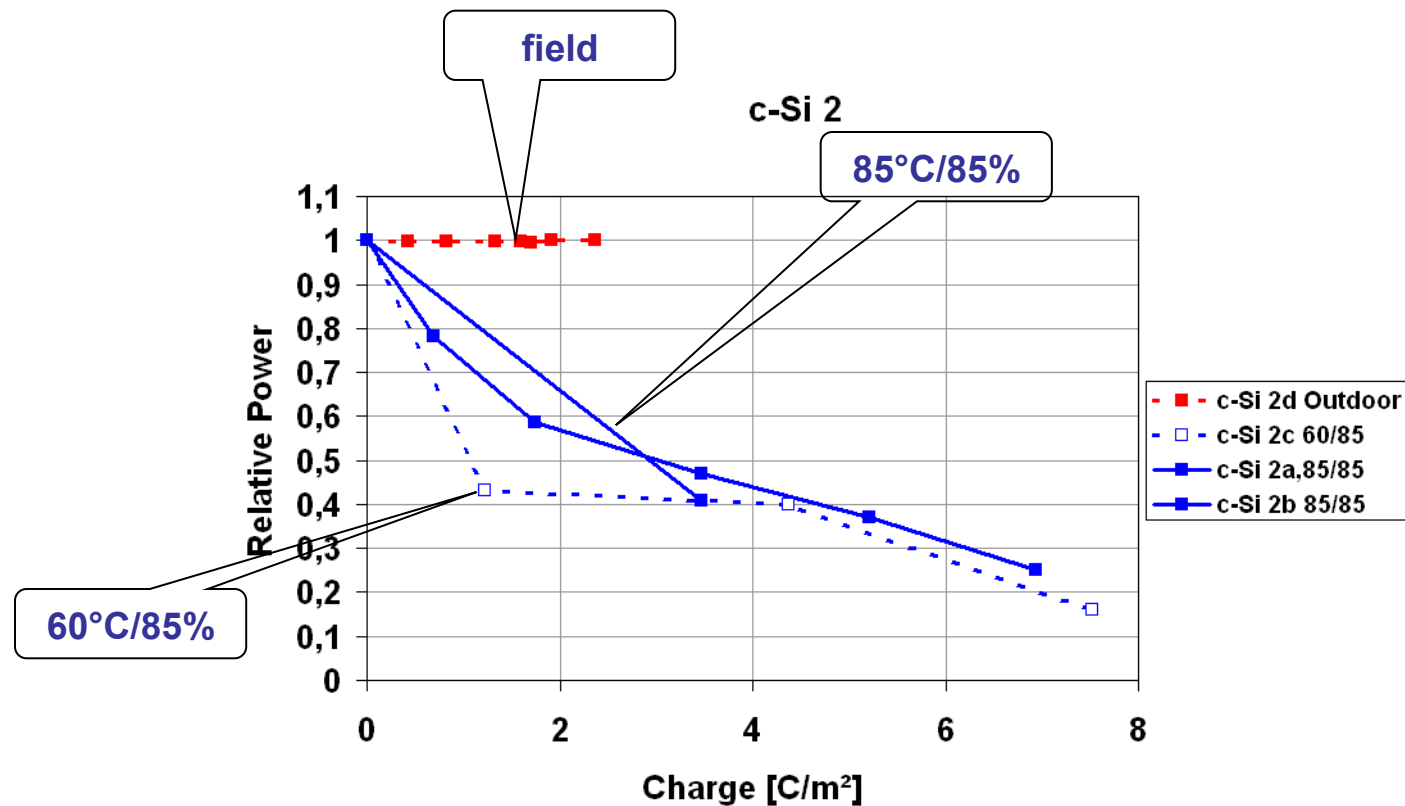
- Match of PID with transferred charge
- Field sample also seems to match with charge (not shown)

Does PID match with transferred charge? (2) Si-TF



- No match of PID (TCO-corrosion) with transferred charge for Si-TF
- $E_a = 1.1$ to 1.2eV for power loss, much higher than E_a for leakage current
- Moisture ingress probably limiting at low temperature

Does PID match with the transferred charge? (3) c-Si



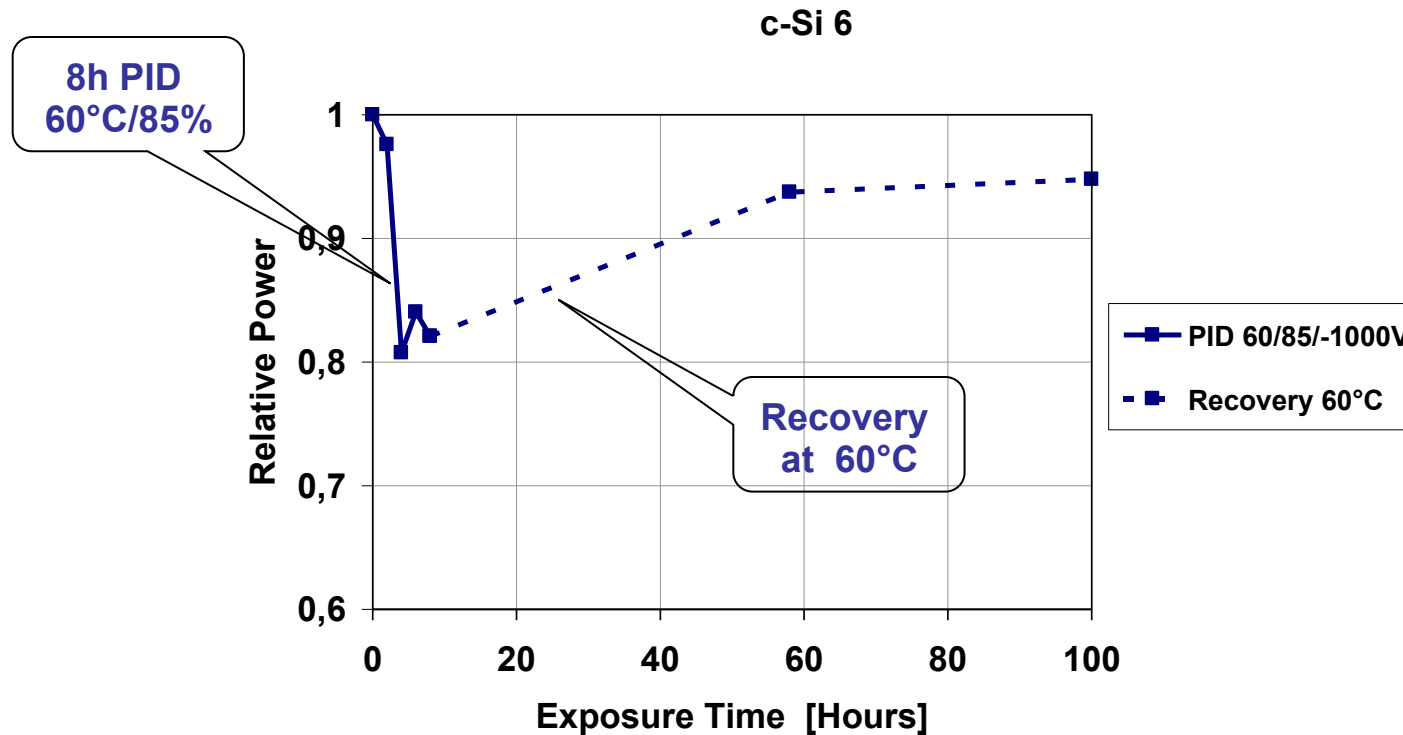
- Possible match of PID with charge for 60/85 and 85/85
- No PID after more than 1 year in the field
- Module type failed IEC62804 test

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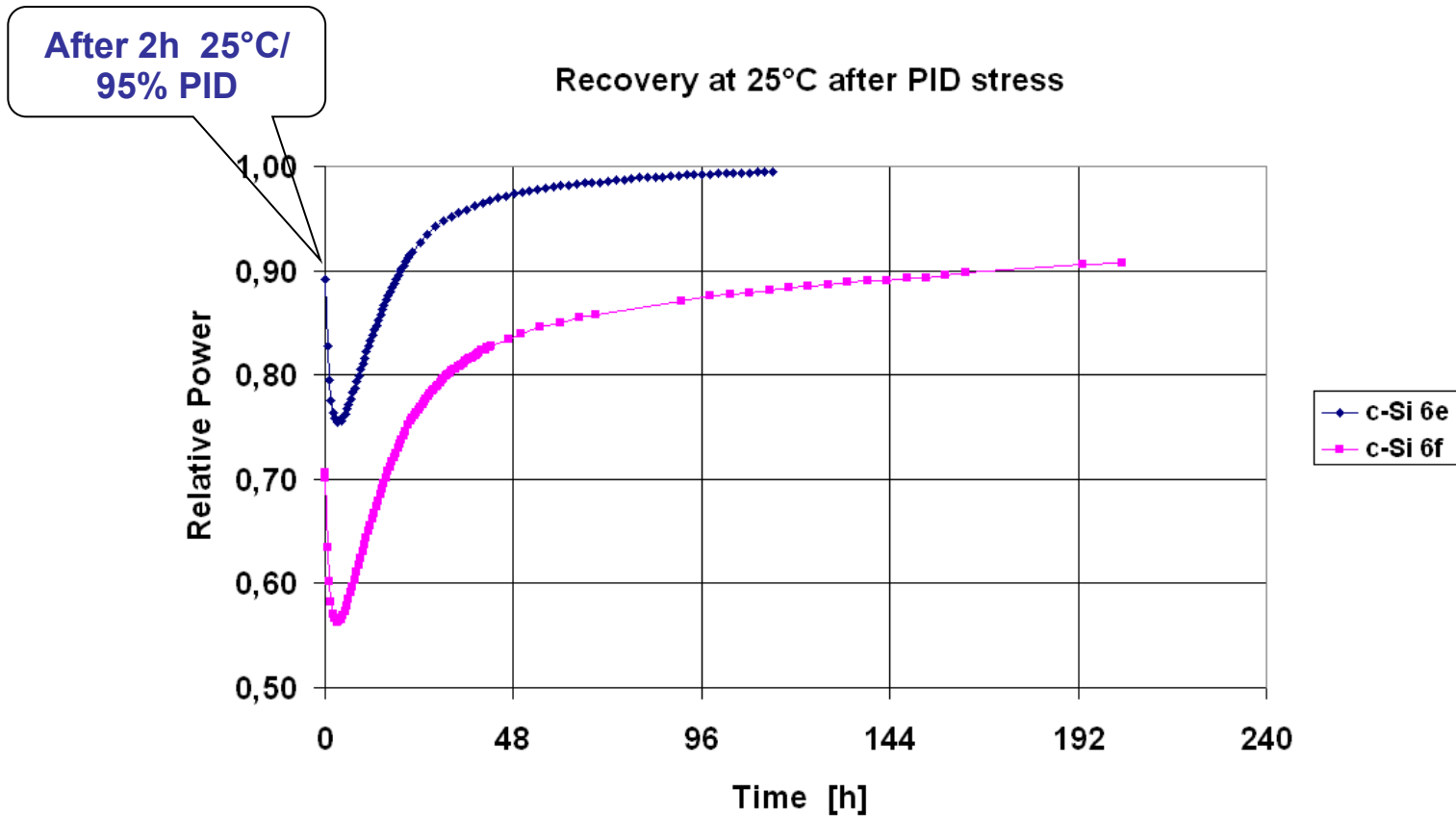


Thermal recovery of c-Si after PID stress



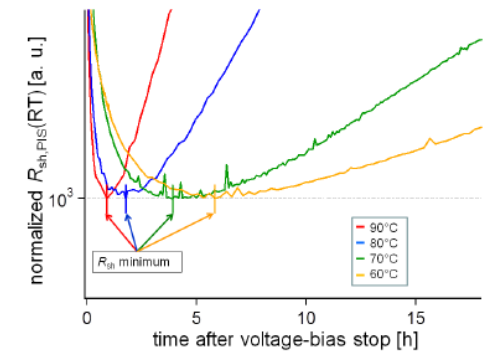
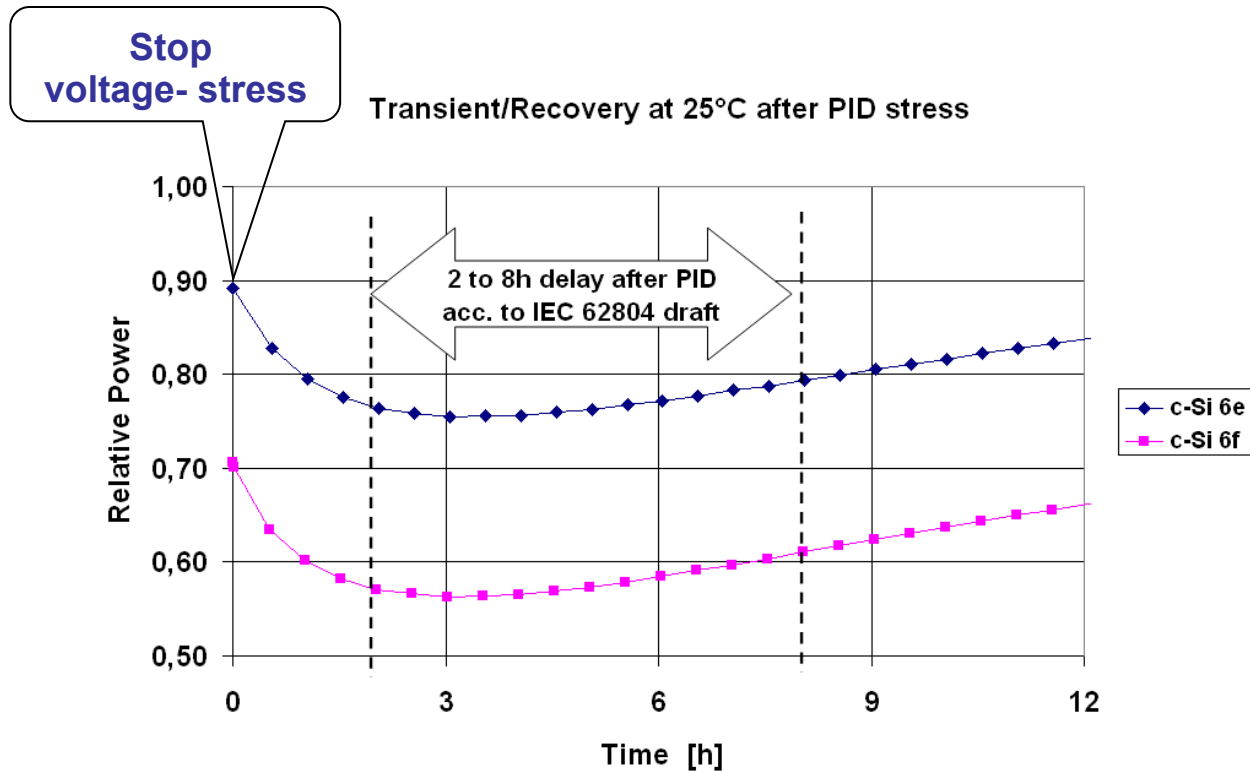
- Thermal recovery at low temperature is relevant for c-Si
- Is important for the field behaviour of c-Si:
balance between periods of leakage current driven PID
and temperature driven recovery

Thermal recovery of c-Si after PID stress (2)



- Relevant recovery even at 25°C possible
- Acceleration at higher T
- E_a is 0.7 to 0.8 eV

Thermal recovery of c-Si after PID stress (2)

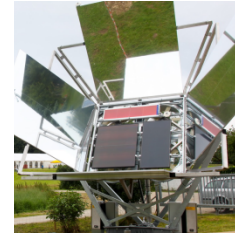


C. Taubitz, EUPVSEC, 2012

- After stop of PID: power degradation continues for hours
- Within the 2 to 8h period after stress (62804 draft): power is not stable

Conclusions and summary

- **Leakage currents are**
 - temperature activated with E_a 0.6 to 0.8eV and
 - significantly driven by humidity
- **CIGS: Correlation of PID (60/85 and 85/85) with transferred charge**
- **Si-TF: No correlation of lab-PID with transferred charge; moisture ingress might be limiting for TCO-corrosion**
- **c-Si:**
 - Correlation with transferred charge definitively not true for PID in the field
 - Thermal recovery from PID at low temperature can be relevant: needs to be addressed in the IEC Draft?
 - Thermal recovery might reduce the “acceleration” of stress tests at high T
 - Balance of leakage current driven degradation and thermal recovery controls PID for c-Si in the field



Thank you for your attention

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Thanks to the ZSW colleagues supporting this work



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